Marking and Labeling of Components, PCBs and PCBAs to Identify Lead (Pb), Lead-Free (Pb-Free) and Other Attributes

A joint standard developed by the Marking, Symbols and Labels for Identification of Assemblies, Components and Devices Task Group (4-34b) of the Materials Identification Subcommittee (4-34) and JEDEC Committee JC14.4 Quality Processes and Methods.

Supersedes:
IPC/JEDEC J-STD-609 - May 2007
JESD97 - May 2004
IPC-1066 - January 2005

Users of this publication are encouraged to participate in the development of future revisions.

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1 SCOPE
This standard applies to components and assemblies that contain Pb-free and Pb-containing solders and finishes. This standard describes the marking of components and the labeling of their shipping containers to identify their 2nd level terminal finish or material, and applies to components that are intended to be attached to boards or assemblies with solder or mechanical clamping or are press fit. This standard also applies to 2nd level terminal materials for bumped die that are used for direct board attach.

This standard applies to boards/assemblies, to identify the type of Pb-free or Pb-containing solder used. This standard documents a method for identifying board surface finishes and Printed Circuit Board (PCB) resin systems. This standard applies to PCB base materials and for marking the type of conformal coating utilized on Printed Circuit Board Assemblies (PCBAs). Material and their containers previously marked or labeled according to JESD 97, IPC-1066, or previous versions of this standard need not be remarked unless agreed upon by the supplier and customer.

Labeling of exterior surfaces of finished articles, such as computers, printers, servers, and the like, is outside the scope of this standard. However, internal PCBs and PCBAs are covered by this standard. Labeling of retail packages containing electronic products is also outside the scope of this standard.

1.1 Purpose
This standard provides a marking and labeling system that aids in assembly, rework, repair and recycling and provides for the identification of:
1) those assemblies that are assembled with Pb-containing or Pb-free solder;
2) components that have Pb-containing or Pb-free 2nd level interconnect terminal finishes and materials;
3) the maximum component temperature not to be exceeded during assembly or rework processing;
4) the base materials used in the PCB construction, including those PCBs that use halogen-free resin;
5) the surface finish of PCBs; and
6) the conformal coating on PCBAs.

2 REFERENCE DOCUMENTS

2.1 IPC
IPC-T-50 Terms and Definitions for Interconnecting and Packaging Electronic Circuits
IPC-CC-830 Qualification and Performance of Electrical Insulating Compound for Printed Wiring Assemblies (Conformal Coating)
IPC-4101 Specification for Base Materials for Rigid and Multilayer Printed Boards

2.2 JEDEC
JESD88 JEDEC Dictionary of Terms for Solid State Technology

2.3 IEC
IEC 61249-2-21 Materials for printed boards and other interconnecting structures - Part 2-21: Reinforced base materials, clad and unclad - Non-halogenated epoxide woven E-glass reinforced laminated sheets of defined flammability (vertical burning test), copper-clad

References:
1. www.ipc.org
2. www.jedec.org
3. www.iec.ch